

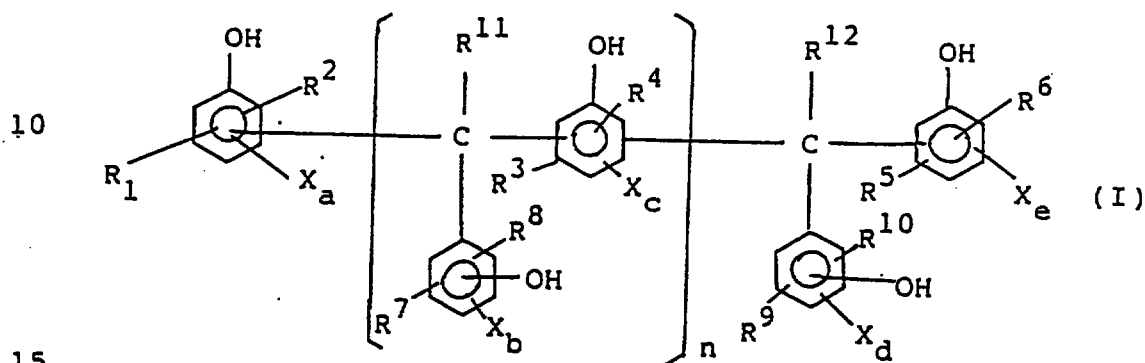


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ABSTRACT

THERMOSETTING RESIN COMPOSITION AND USE THEREOF
FOR AN ELECTRONIC PART

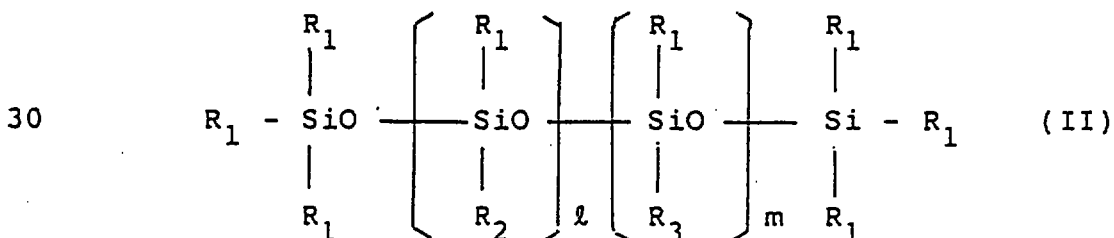
5 A thermosetting resin composition is provide,
 which contains a compound of



wherein substituents $R_1 - R_6$ each represents a hydrogen atom or a saturated alkyl group having 1 - 6 carbon atoms, substituents $R_7 - R^{12}$ each represents a hydrogen atom, a saturated alkyl group having 1 - 4 carbon atoms or an alkoxy group having 1 - 4 carbon atoms, $X_a - X_e$ each represents a hydrogen atom, a chlorine atom or a bromine atom, and the average repeating unit number n denotes a numeral from 0 to 5,

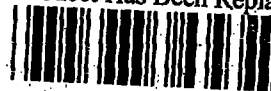
20 and a polyamide compound having two or more maleimide groups and, if desired, a compound of

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wherein R_1 and R_2 each represents a methyl group or a phenyl group, and R_3 represents a hydrogen atom or a functional group containing an amino group, a glycidyl

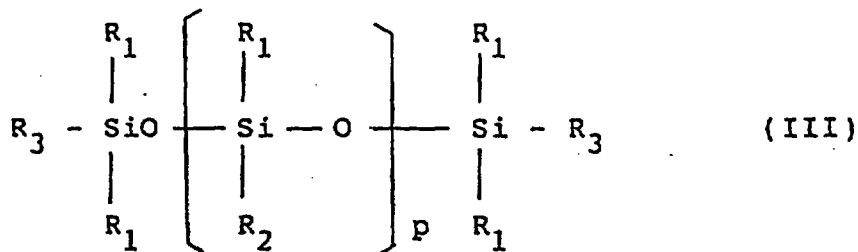
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group or an alicyclic epoxy group, l denotes a numeral in the range of 0 - 500, and m denotes a numeral in the range of 1 - 500, or

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wherein R_1 and R_2 each represents a methyl group or a phenyl group, and R_3 represents a hydrogen atom or a functional group containing an amino group, a glycidyl group or an alicyclic epoxy group, and p denotes a numeral in the range of 0 - 500. The composition is useful for electronic parts.

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